



THE DATASHEET OF SF2211E



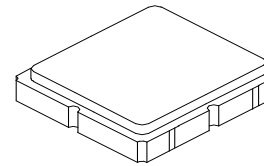
SF2211E

**1200 MHz
SAW Filter**

- **No Matching Network Required for 50 Ω Operation**
- **Surface-mount 3.0 x 3.0 mm Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-55 to +85	$^{\circ}$ C
Storage Temperature Range in Tape and Reel	-40 to +85	$^{\circ}$ C
Component Storage Temperature Range	-55 to +95	$^{\circ}$ C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	$^{\circ}$ C



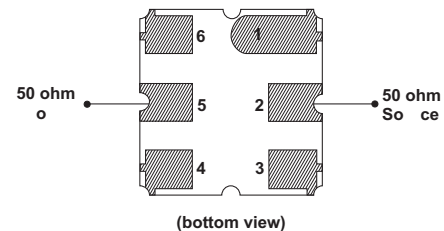
SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1200		MHz
Insertion Loss, 1180 to 1220 MHz	IL			2.8	4.0	dB
Attenuation, 0 dB Reference:						dB
1080 MHz			35	60		
1100 MHz			45	60		
1300 MHz			40	48		
1320 MHz			35	52		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	945, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel				
	Reel Size 13 Inch	3000 Pieces/Reel				

Electrical Connections

Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

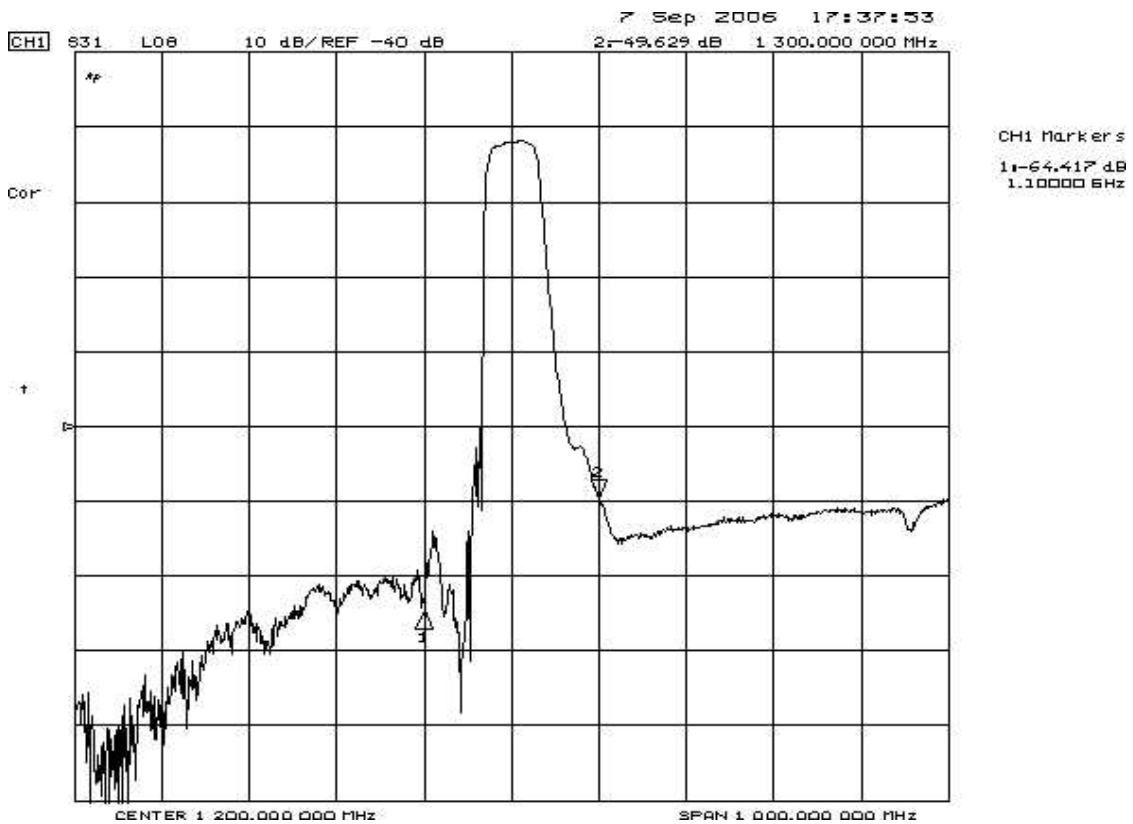
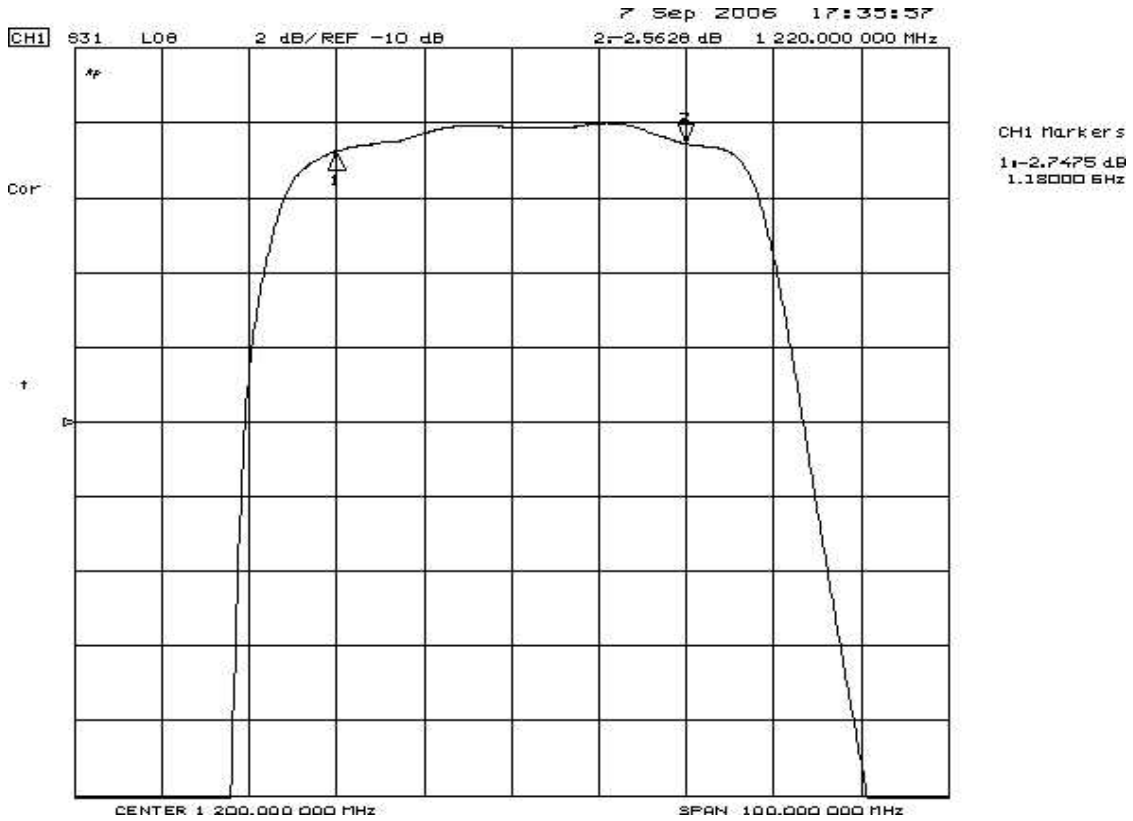


 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

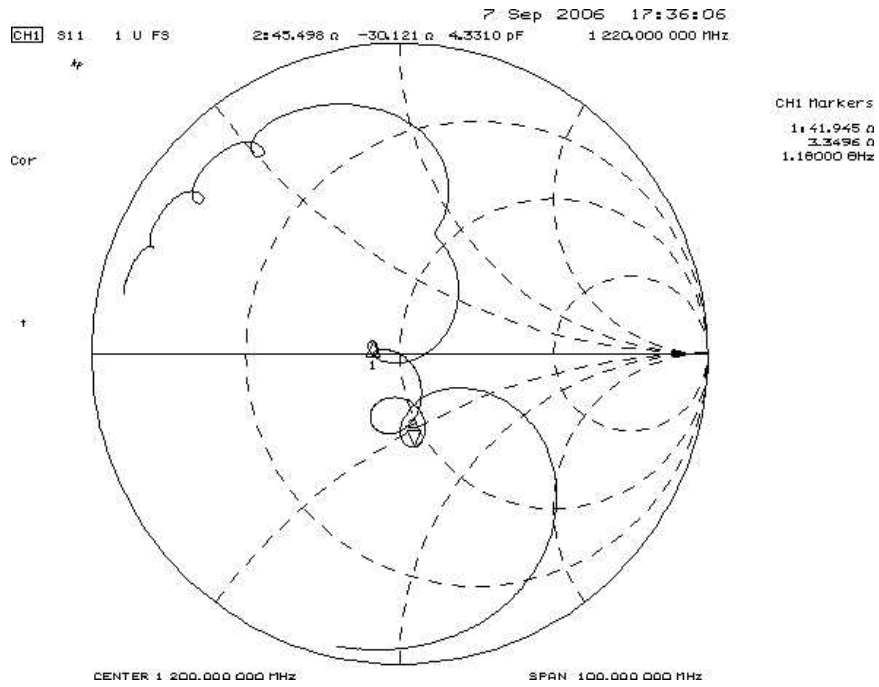
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

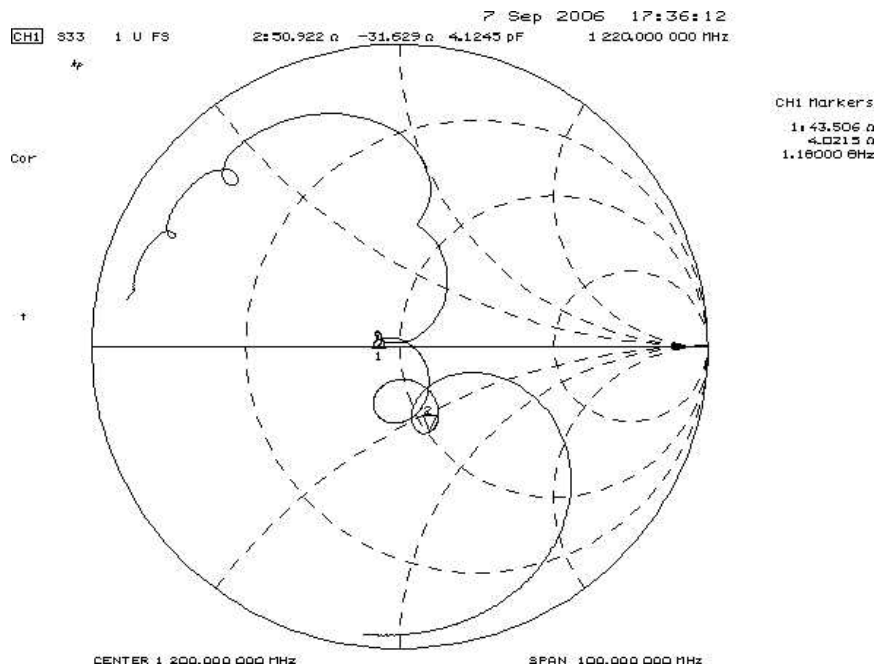
Filter Frequency Response



Filter Input Impedance



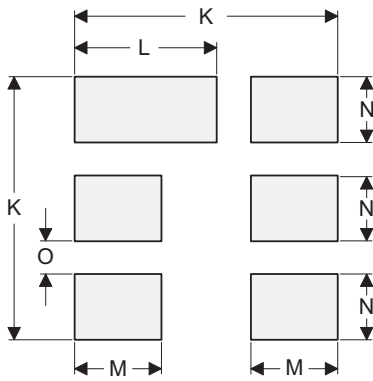
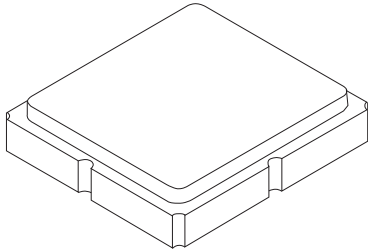
Filter Output Impedance



SM3030-6 Case

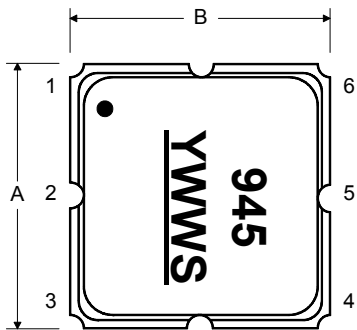
6-Terminal Ceramic Surface-Mount Case

3.0 X 3.0 mm Nominal Footprint

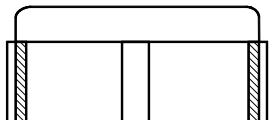
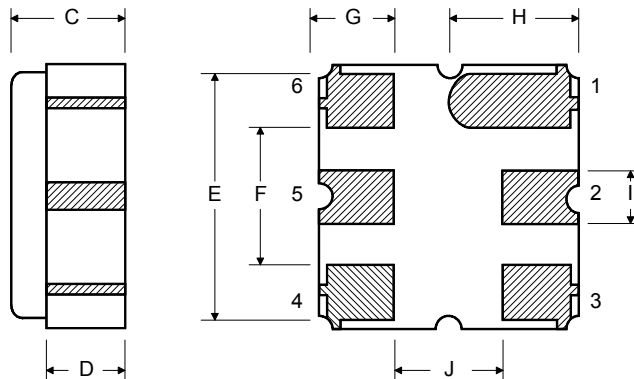


PCB Footprint Top View

Top View



Bottom View



Case and PCB Footprint Dimensions

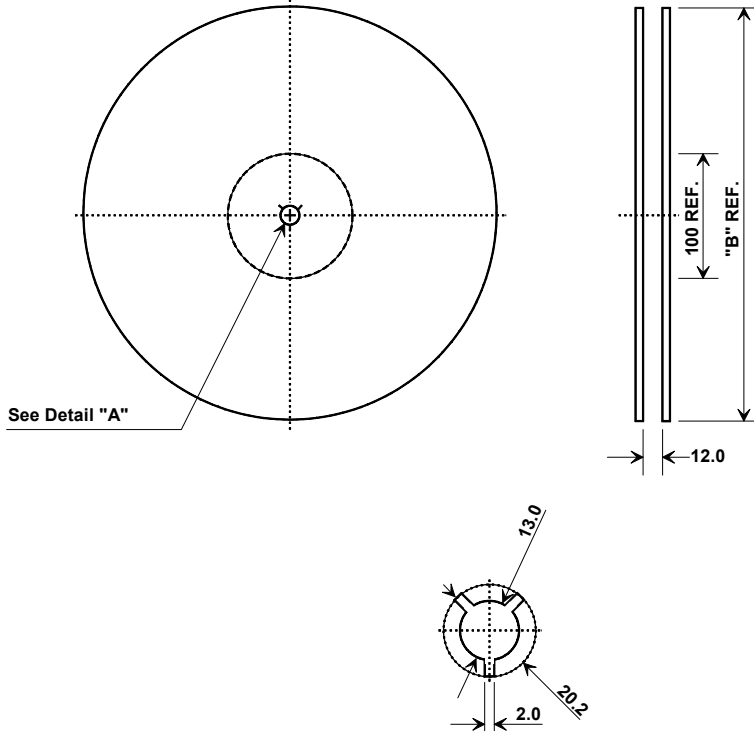
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

Tape and Reel Specifications

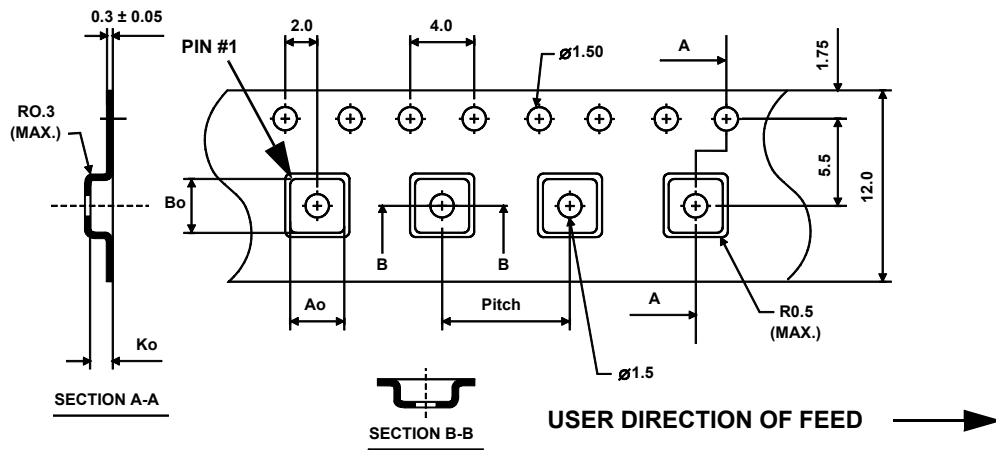
Tape and Reel Standard per ANSI/EIA-481



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

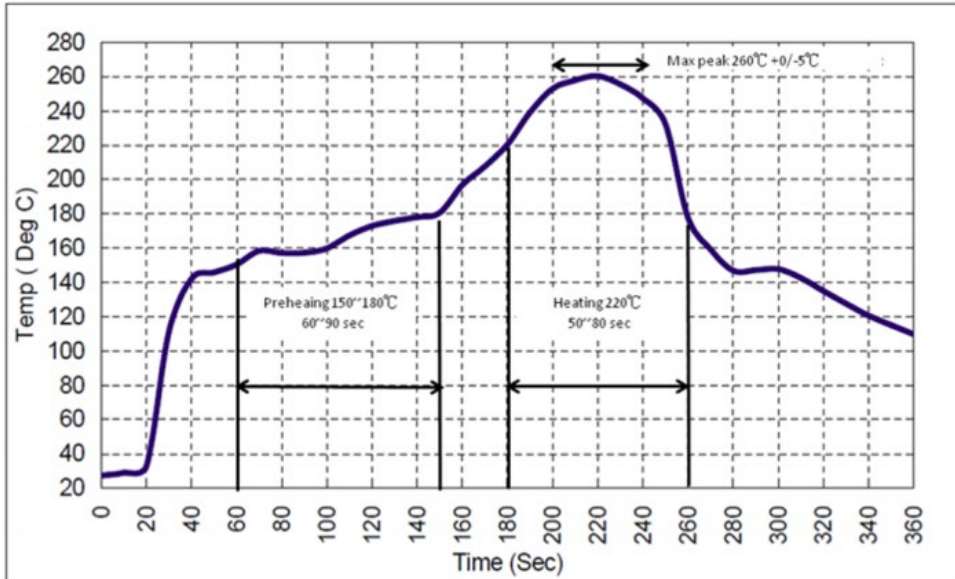
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm





Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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